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(54) **Title:** FLATNESS PRECISION IMPROVEMENT WITH SYSTEMATIC ERROR REDUCTION VIA INDUCED WAFER TILT VARIATION

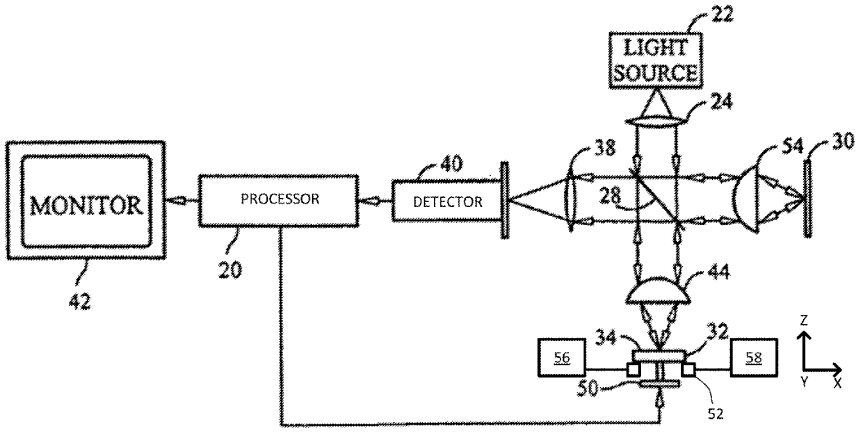


FIG. 7

(57) **Abstract:** A workpiece is placed on a stage in an interferometer. Measurements of the workpiece are taken using the interferometer. A random two-dimensional tilt is applied to the workpiece before each of the measurements using at least one tilt motor. A stage is configured to hold a workpiece in a path of the beam of light from a beam splitter. The tilt motor is connected with the stage and randomly move the stage in two dimensions before a measurement..

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